## 1.27MM PITCH SLIM-GRID<sup>®</sup> UNSHROUDED HEADERS (BOARD TO BOARD)

### 1.0 SCOPE

This Product Specification covers the 1.27mm centerline (pitch) printed circuit board (PCB) connector series

### 2.0 PRODUCT DESCRIPTION

## 2.1 PRODUCT NAME AND SERIES NUMBER(S)

**Product Name Series Number** 

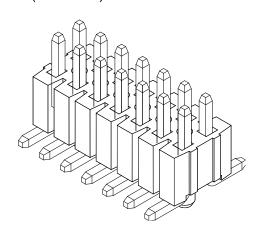
1.27mm Pitch SLIM-GRID<sup>®</sup> Unshrouded Headers 87933

## 2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

See Sales Drawings, SD-87933-0001, SD-87933-014, SD-87933-100 and SD-87933-101 for information on dimensions, materials, plating, and markings.

## 2.3 SAFETY AGENCY APPROVALS

UL FILE NUMBER : File E29179, Vol 10 152514 (LR 19980) **CSA FILE NUMBER:** 



### 3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

The following documents form a part of this specification to the extended specified herewith. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence.

## Reference Product Specifications

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1.27mm Pitch SLIM-GRID® Vertical SMT Receptacle 781200001

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## 4.0 RATINGS

## 4.1 VOLTAGE

125 Vac

## **4.2 CURRENT**

4.3 Amps per Pole

## 4.3 TEMPERATURE

Operating:  $-55^{\circ}$ C to  $+105^{\circ}$ C Non-operating:  $-\overline{55}^{\circ}$ C to  $+\overline{105}^{\circ}$ C

Safety rating serves as a guideline for safe use to customer. The performance of the current and voltage rating varies at mating level. The connector must be evaluated in the customer end product for safe and proper us

## **5.0 PERFORMANCE**

## **5.1 ELECTRICAL REQUIREMENTS**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	Contact Resistance (LLCR)	Mate connectors: apply a maximum voltage of <b>20</b> mV and a current of <b>100</b> mA. (EIA-364-23)  Note: Wire resistance and traces shall be removed from the measured value.	<b>30</b> milliohms [MAXIMUM] [initial]
2	Insulation Resistance	Mated & unmount connectors: apply a voltage of <b>500</b> VDC between adjacent terminals and between terminals to ground.  (EIA-364-21)	1000 Megohms [MINIMUM]
3	Dielectric Withstanding Voltage	Mated & unmount connectors: apply a voltage of 1000VAC for 1 minute between adjacent terminals and between terminals to ground.  Unmate & unmount connectors: apply a voltage of 1250VAC for 1 minute between adjacent terminals and between terminals to ground.  (EIA-364-20)	No breakdown; Current leakage < <b>5</b> mA

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4	Mate connectors at Full Loading: measure the temperature rise of the contact when 1.4A DC current is passed.	Temperature rise: +30°C [MAXIMUM]
	(EIA-364-70, Method 1)	

## **5.2 MECHANICAL REQUIREMENTS**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5	Connector Mate & Unmate Force	Mate and unmate connectors at a rate of <b>25.4 mm/min</b> (EIA-364-13D, Method A)	Mate Force 15N (24ckt) 10N (4ckt) [MAXIMUM]  Unmate Force 3.0N (24ckt) 0.5N (4ckt) [MINIMUM]
6	Durability	Mate connectors up to <b>50</b> cycles at a maximum rate of <b>500</b> ± <b>50</b> cycles/hr.  (EIA-364-09)	Appearance: No Damage  Contact Resistance:  15milliΩ  [MAXIMUM]  [CHANGE FROM INITIAL]
7	Reseating	Manually mate and unmate the connector with mating half for <b>3 cycles</b> with rate of <b>5 cycles/min</b> maximum.  (EIA-364-09)	Appearance: No Damage  Contact Resistance:  15milliΩ  [MAXIMUM]  [CHANGE FROM INITIAL]
8	Terminal Retention Force (in Housing)	Axial pullout force on the terminal in the housing at a rate of 25 ± 6 mm (1 ± ¼ inch) per minute.  (EIA-364-29, Method C)	<b>4.0 N</b> [MINIMUN]

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9	Vibration	Mate connectors and subject to the following vibration conditions, for a period of <b>2 hours</b> in each 3 mutually perpendicular axis.  Amplitude: <b>1.52mm</b> (.060 inch) peak to peak Test pulse: <b>half sine</b> Sweep: <b>10-&gt;55-&gt;10 Hz</b> in <b>1 minute</b> Duration: <b>2 hours</b> in each x-y-z axis.  (EIA-364-28, Test Condition I)	Appearance: No Damage  15milliohms [MAXIMUM] (change from initial)  Discontinuity: 1.0 µs [maximum]
10	Mechanical shock	Mate connectors and subject to the following shock conditions, 3 shocks shall be applied along 3 mutually perpendicular axis. (total of 18 shocks)  Peak value: <b>490</b> m/s sq. (50G)  Test pulse: <b>half sine</b> Duration: <b>11 ms</b> in each x-y-z axis  (EIA-364-27B Condition A)	
11	Thermal shock	Mate connectors, expose to 5 cycles of:-  Temperature °c Duration (minutes)  -55+0/-5 30  Transfer time from cold to hot +105+3/-0 30  Transfer time from hot to cold  (EIA-364-32G Method A, Condition VII)	Appearance: No Damage  Contact Resistance:  15milliΩ  [MAXIMUM]  [CHANGE FROM INITIAL]
12	Temperature life	Mate connectors, expose to:-  Temperature: <b>105 ± 2</b> °c  Duration: <b>96</b> hours.  (EIA-364-17, Method A, Condition 4)	Appearance: No Damage  Contact Resistance:  15milliΩ  [MAXIMUM]  [CHANGE FROM INITIAL]

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# molex<sup>®</sup> PRODUCT SPECIFICATION

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13	Cyclic temperature and humidity	Mate connector and expose to:-  Temperature: 25 ± 3 °C @ Humidity: 80% ± 3% And Temperature: 65 ± 3 °C @ Humidity: 50% ± 3% Ramp times should be 0.5 hour and dwell times should be 1.0 hour. Dwell times start when the temperature and humidity have stabilized within the specified levels. Duration: 24 cycles (72 hours)	Appearance: No Damage  Contact Resistance:  15milliΩ  [MAXIMUM]  [CHANGE FROM INITIAL]  Dielectric withstanding  Voltage:  No breakdown  Insulation resistance:  1000 megaΩ minimum
14	Low temperature test	Mate connectors and expose to:  Temperature: -40 ± 3°C Duration: 96 +5/-0 hours  (EIA-364-59A)	Appearance: No Damage  Contact Resistance:  15milliΩ  [MAXIMUM]  [CHANGE FROM INITIAL]
15	SO₂ gas (gold plated only)	Mate connectors and expose to:  SO <sub>2</sub> gas density: <b>50 ±5</b> ppm Temperature: <b>40 ±2</b> °C Duration: <b>24 hours</b> Humidity: <b>60-75%</b> .	Appearance: No Damage  Contact Resistance:  15milliΩ  [MAXIMUM]  [CHANGE FROM INITIAL]
16	Salt spray	Expose the mated connectors to the following salt mist condition:  Concentration: 5 ±1% Temperature: 35 +1/-2°C Test time: 48 hours  (note: immediately after exposure, the test specimens shall be dipped in running tap (≤38°C) for 5 mins max and dried for 16 hour max in a circulating air oven at 38 ± 3°C. Sample examination done in room temperature.  (EIA-364-26C, Condition B)	Appearance: No Damage  Contact Resistance: 15milliΩ [MAXIMUM] [CHANGE FROM INITIAL]

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17	Solderability	Unmate connector.  Steam age for 8 hour ± 15 min. (precondition: Condition C)  SMT  Surface mount process simulation test Solder paste is deposited onto screen (e.g.ceramic plate) via stencil.  The connectors are placed onto the solder paste print.  Subject the substrate and component to the reflow process through a convection oven.  Refer to section 8.0 for temperature profile.  Flux type: ROL0	95% of the immersed area must show no voids, pin holes
18	Resistance to solder Heats	SMT Convection reflow Sample to be passed through reflow over according to temperature profiles (shown in section 8.0) (EIA-364-56C, Procedure 6)	Appearance: no damage

## 6.0 PACKAGING

Parts shall be packaged to protect against damage during handling, transit and storage. Refer to Packaging Specification, PK-87933-565 AND PK-87933-300

## 7.0 OTHERS

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Although some discolouration could be seen on the soldertail after reflow, it does not impact on the product's performance.

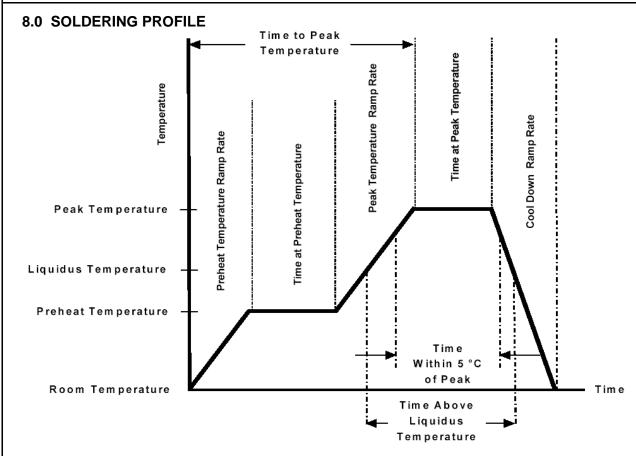
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## 7.0 TEST SEQUENCES

Sequential Tests Group ->	1	2	3	4	5	6	7	8	9	10	11
Test or Examination <b>Ψ</b>											
Sample size	5	5	5	5	5	5	5	5	5	5	5
Resistance to Soldering Conditions	1	1	1	1	1	1	1	1			
Low Level Contact Resistance (LLCR)	2, 5, 7	2, 5, 7, 9			2, 4	2, 4	2, 4	3, 7			
Insulation Resistance				2, 6							
Dielectric Withstanding Voltage				3, 7							
Connector Mate								2, 6			
Connector Unmate								4, 8			
Durability	3(a)	3(a)	3(a)					5			
Reseating	6	8									
Vibration			6								
Mechanical Shock			8								
Thermal Shock		4		4							
Temperature Life	4		4(a)								
Cyclic Temperature & Humidity		6		5							
Low Temperature Test					3						
SO <sub>2</sub> gas (Gold plated)						3					
Salt Spray							3				
Pin Retention (in housing)									1		
Solderability										1	
Temperature Rise											1

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Description	Requirement			
Average Ramp Rate	3°C/sec Max			
Preheat Temperature	150°C Min to 200°C Max			
Preheat Time	60 to 180 sec			
Ramp to Peak	3°C/sec Max			
Time over Liquidus (217°C)	60 to 150 sec Max			
Peak Temperature	260 +0/-5°C			
Time within 5°C of Peak	20 to 40 sec			
Ramp - Cool Down	6°C/sec Max			
Time 25 °C to Peak	8 Min Max			

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